

FDA18N50

N-Channel UniFET™ MOSFET

500 V, 19 A, 265 mΩ

Features

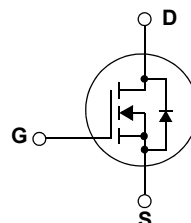
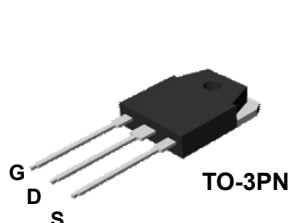
- $R_{DS(on)} = 265 \text{ m}\Omega$ (Max.) @ $V_{GS} = 10 \text{ V}$, $I_D = 9.5 \text{ A}$
- Low Gate Charge (Typ. 45 nC)
- Low C_{rss} (Typ. 25 pF)
- 100% Avalanche Tested

Applications

- PDP TV
- Uninterruptible Power Supply
- AC-DC Power Supply

Description

UniFET™ MOSFET is Fairchild Semiconductor®'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



Absolute Maximum Ratings

Symbol	Parameter		FDA18N50	Unit
V_{DSS}	Drain-Source Voltage		500	V
I_D	Drain Current	- Continuous ($T_C = 25^\circ\text{C}$)	19	A
		- Continuous ($T_C = 100^\circ\text{C}$)	11.4	A
I_{DM}	Drain Current	- Pulsed (Note 1)	76	A
V_{GSS}	Gate-Source voltage		± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	945	mJ
I_{AR}	Avalanche Current	(Note 1)	19	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	23	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	239	W
		- Derate above 25°C	1.92	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FDA18N50	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.52	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDA18N50	FDA18N50	TO-3PN	-	-	30

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	500	--	--	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	--	0.5	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V V _{DS} = 400V, T _C = 125°C	-- --	-- --	1 10	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	3.0	--	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 9.5A	--	0.220	0.265	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 9.5A	--	25	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	--	2200	2860	pF
C _{oss}	Output Capacitance		--	330	430	pF
C _{rss}	Reverse Transfer Capacitance		--	25	40	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 250V, I _D = 19A R _G = 25Ω (Note 4)	--	55	120	ns
t _r	Turn-On Rise Time		--	165	340	ns
t _{d(off)}	Turn-Off Delay Time		--	95	200	ns
t _f	Turn-Off Fall Time		--	90	190	ns
Q _g	Total Gate Charge	V _{DS} = 400V, I _D = 19A V _{GS} = 10V (Note 4)	--	45	60	nC
Q _{gs}	Gate-Source Charge		--	12.5	--	nC
Q _{gd}	Gate-Drain Charge		--	19	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	19	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	76	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 19A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 19A	--	500	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt =100A/μs	--	5.4	--	μC

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 4.7mH, I_{AS} = 19A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C
3. I_{SD} ≤ 19A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

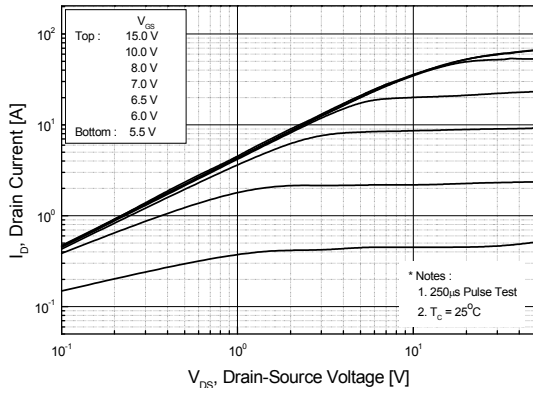


Figure 2. Transfer Characteristics

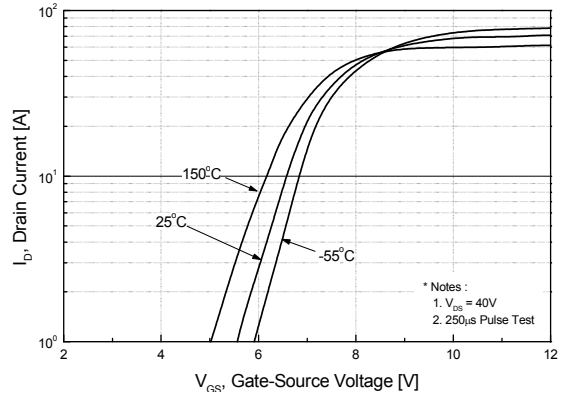


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

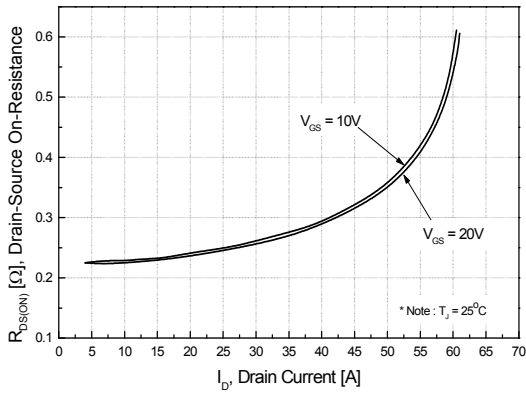


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

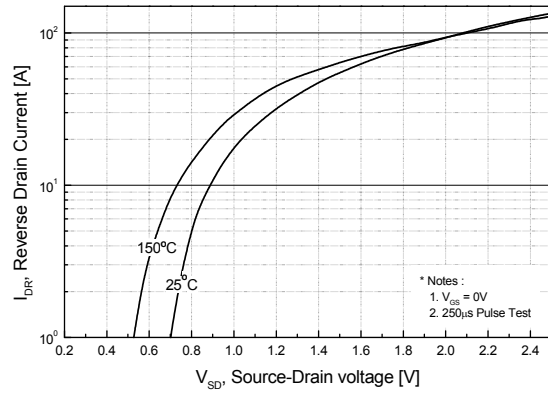


Figure 5. Capacitance Characteristics

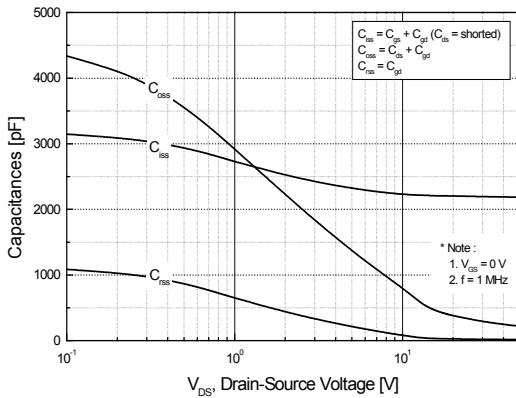
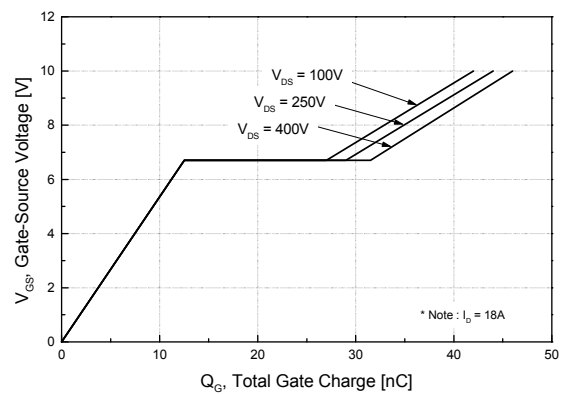


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

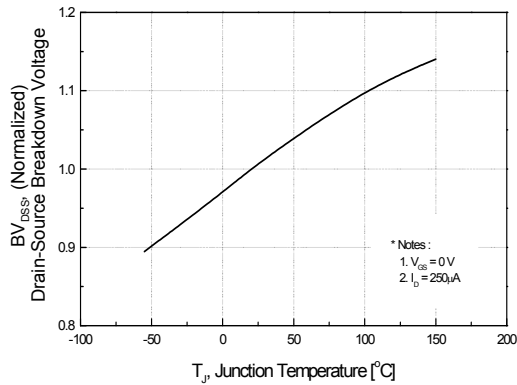


Figure 8. On-Resistance Variation vs. Temperature

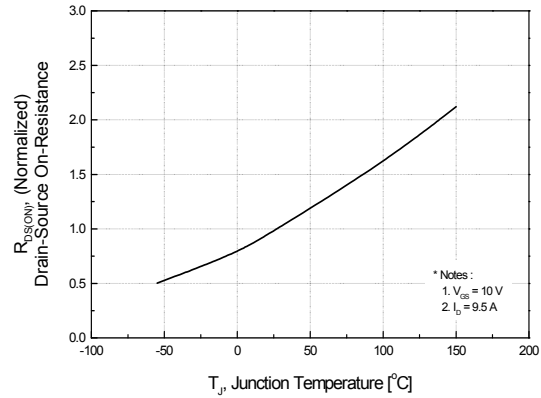


Figure 9. Maximum Safe Operating Area

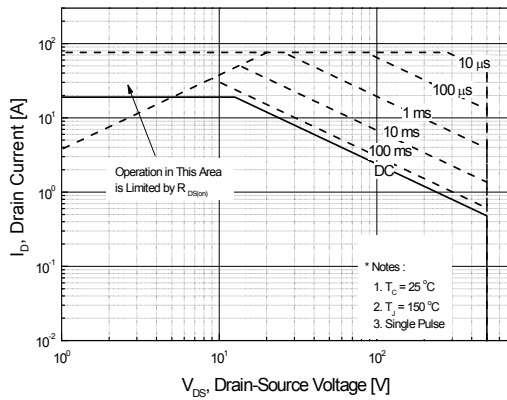


Figure 10. Maximum Drain Current vs. Case Temperature

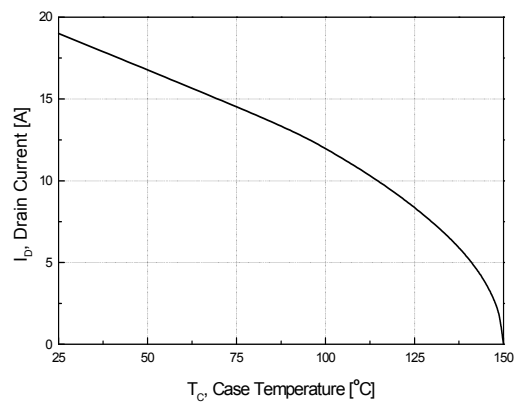
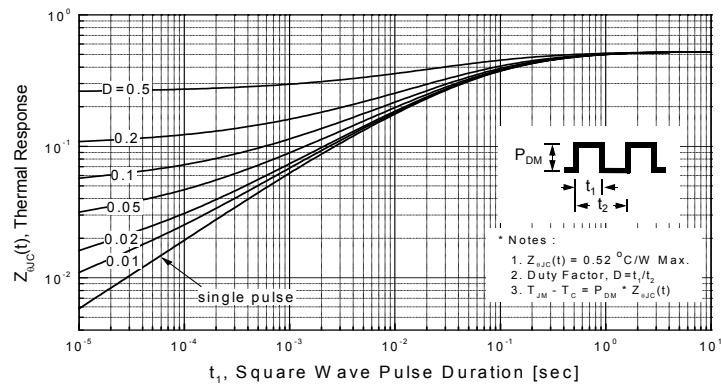
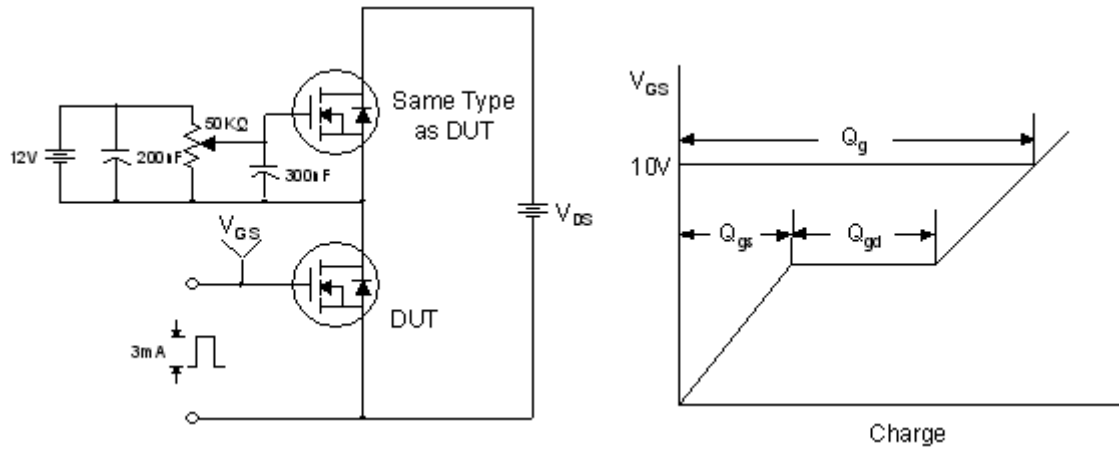


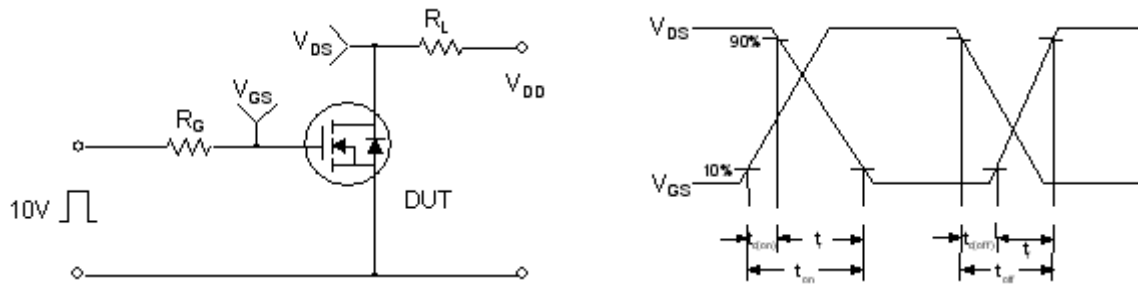
Figure 11. Transient Thermal Response Curve



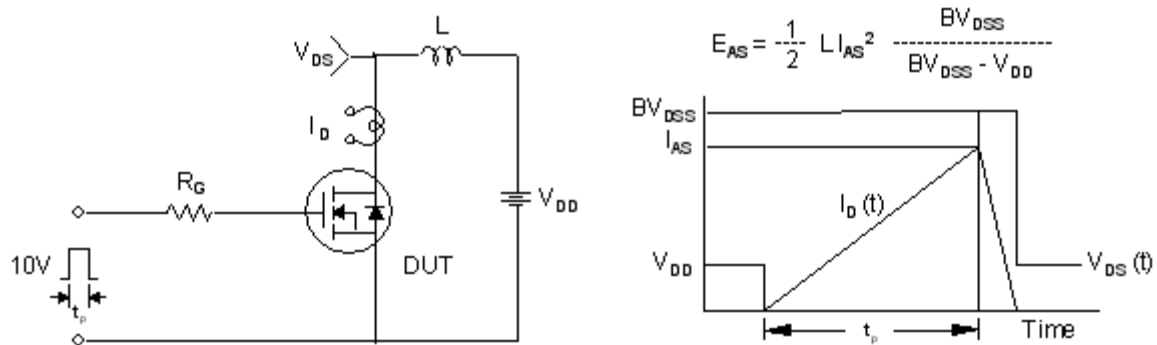
Gate Charge Test Circuit & Waveform



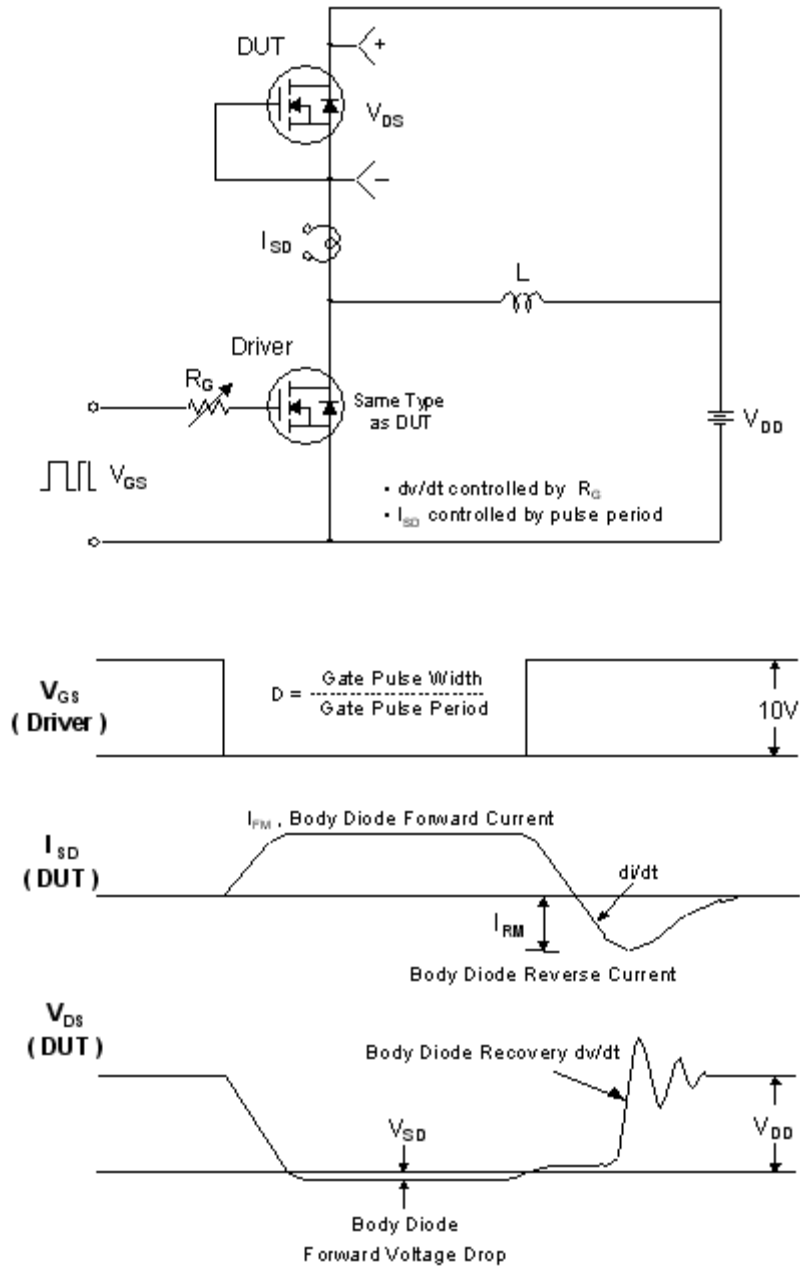
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



Technical drawing of a 3-pin TO-18 package showing front, side, and top views with dimensions in mm.

Front View Dimensions:

- Top width: 15.80 / 15.40
- Top height: 5.20 / 4.80
- Bottom height: 20.10 / 19.70
- Right side height: 18.90 / 18.50
- Pin 1 width: 1.85
- Pin 2 width: 2.20 / 1.80
- Pin 3 width: 1.20 / 0.80
- Pin 1 height: 3.70 / 3.30
- Pin 2 height: 3.20 / 2.80
- Pin 3 height: 3.20 / 2.80
- Pin 1 pitch: 5.45
- Pin 2 pitch: 5.45
- Pin 3 pitch: 5.45
- Pin 1 diameter: $\varnothing 0.55$ (M)

Side View Dimensions:

- Top width: 5.00 / 4.60
- Top height: 1.65 / 1.45
- Pin 1 height: 3°
- Pin 2 height: 3°
- Pin 3 height: 4°
- Pin 1 pitch: 2.90 / 1.90
- Pin 2 pitch: 0.75 / 0.55
- Pin 3 pitch: 0.75 / 0.55

Top View Dimensions:

- Top width: 13.80 / 13.40
- Top height: 16.96 / 16.56
- Pin 1 height: 20.30 / 19.70
- Pin 2 height: 20.30 / 19.70
- Pin 3 height: 20.30 / 19.70
- Pin 1 pitch: 5.45
- Pin 2 pitch: 5.45
- Pin 3 pitch: 5.45
- Pin 1 diameter: $\varnothing 3.30$ / 3.10
- Pin 2 diameter: $\varnothing 7.20$ / 6.80
- Pin 3 diameter: $\varnothing 7.20$ / 6.80

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